

- (3) Patent Abstracts of Japan, Vol. 1999, No. 5, May 31, 1999, JP-11050023;
- (4) Patent Abstracts of Japan, Vol. 1998, No. 11, September 30, 1998, JP-10165391; and
- (5) European Patent Application 0 969 267, published January 5, 2000 to General Electric Company.

Copies of the aforementioned patent documents and a listing on PTO-1449 are enclosed herewith.

The above-referenced patent documents were cited in a search report issued in a corresponding European patent application within three months of the date of this communication.

Japanese Patent Publication No. 58 135954 relates to a magnetic flaw detector.

Japanese Patent Publication No. 11 050023 relates to an adhesive tape subsuming metal wire in which a plastic tape acts as a substrate, a metal wire is fitted to one side of the plastic tape in a longer direction, thermally fused preferably in a subsumed state, a double coated adhesive tape is laminated and bonded to the plastic tape and the top of the metal wire, and a release tape is integrally formed to give the objective adhesive tape.

Japanese Patent Publication No. 10 165391 relates to a diagnostic or therapeutic marker for magnetic resonance image diagnostic device or CT device. A plastic sheet constitutes a sheet-type marker and has a magnetic tape and a non-magnetic metal wire nipped between it and a plastic sheet and is formed of a double surfaced adhesive tape so as to be adhesive to the skin of a subject. The non-magnetic metal wire is nipped in the state layered on the magnetic tape between the plastic sheet and a second plastic sheet formed of the double-surfaced adhesive tape.

International Publication No. 98/37564 relates to a surface-mount fuse for protecting a circuit which includes a substrate having first and second surfaces. The fuse includes a metal strip attached to the first surface of the substrate with a layer of adhesive material, the layer of adhesive material being disposed between the metal strip and the first surface of the substrate. The metal strip has a first connection region, second connection region and a non-linear fuse link between. The fuse further includes first and second wire leads conductively connected to the connection regions for connecting the fuse to the remainder of the circuit.

European Patent Application No. 0 969 267 relates to a system and method for normalizing and calibrating a sensor array. The sensor array can comprise different elemental

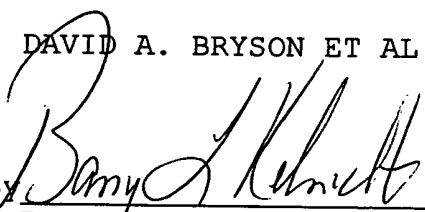
sensors such as for example eddy current sensors or absolute sensors. A single test specimen is used to normalize and calibrate the sensor array using one or more scans of the test specimen. The test specimen is preferably made of the same or similar type of material as the part to be tested and is of a similar geometric shape that can have a simple flat surface or more complex surface. A linear feature and several notches are machined into the surface of the specimen by using for example electrodischarge machining methods to provide the necessary signals when scanned by the sensor array.

None of the above-referenced documents are believed to negate the patentability of the present invention.

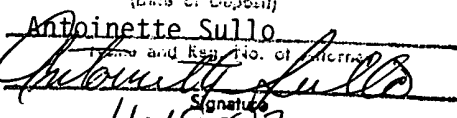
If any charges are required in connection with this submission, it is requested that they be charged to Deposit Account No. 02-0184.

Respectfully submitted,

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